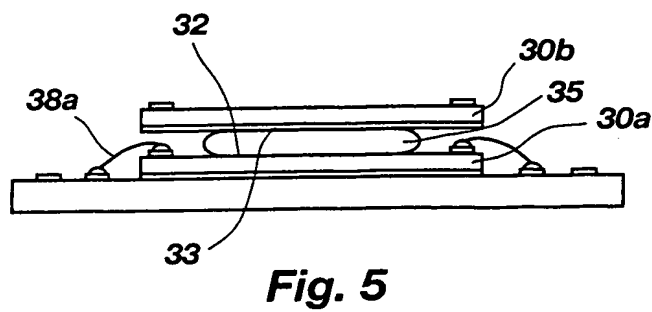
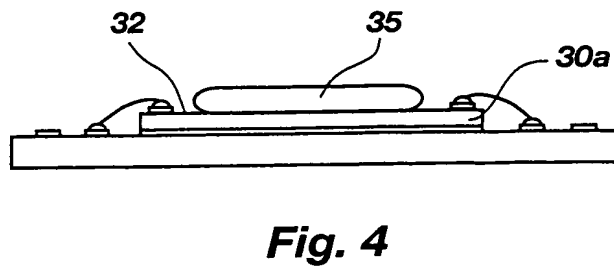
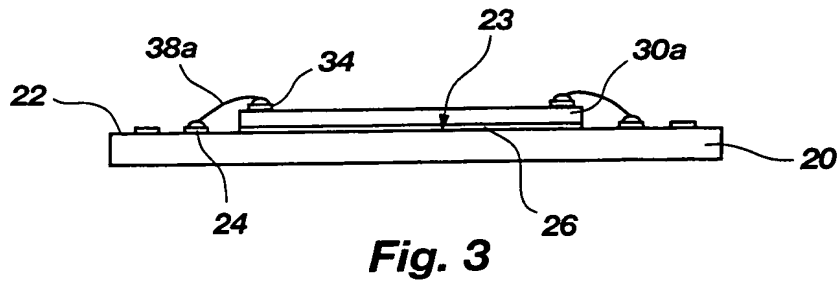
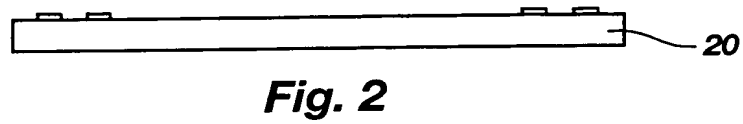
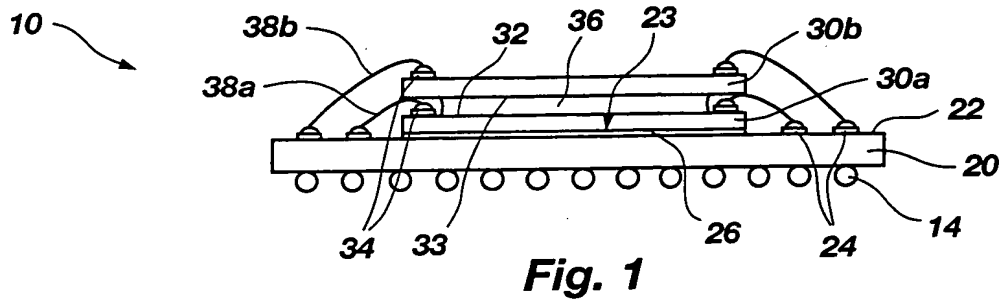


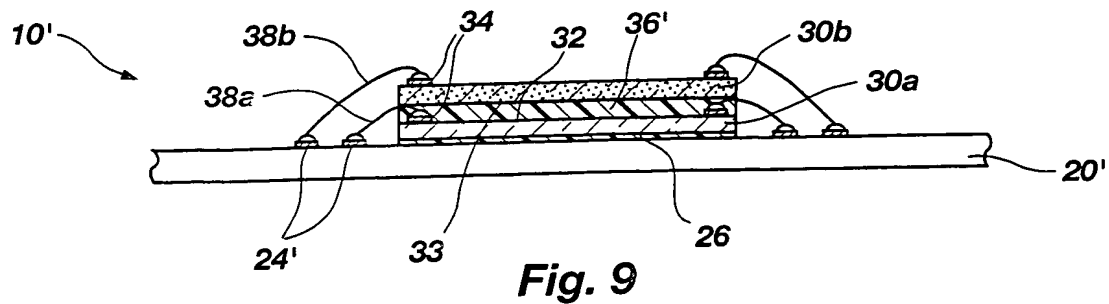
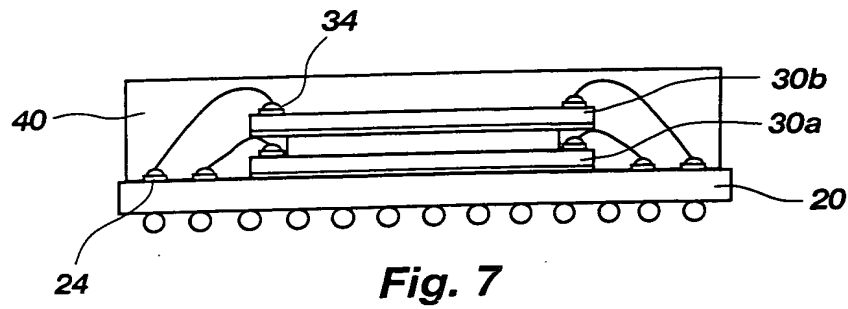
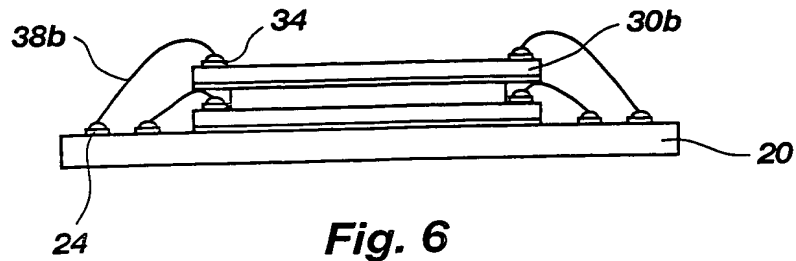
TITLE: METHODS FOR FORMING ASSEMBLIES AND PACKAGES
THAT INCLUDE STACKED SEMICONDUCTOR DEVICES
SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL
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Inventor: J. Derderian
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